

XG0066(XG3012)

N-Channel Enhancement Mode SGT MOSFET

40V(VDS) / ± 20 V(VGS) / 198A(ID)

Rev0.2

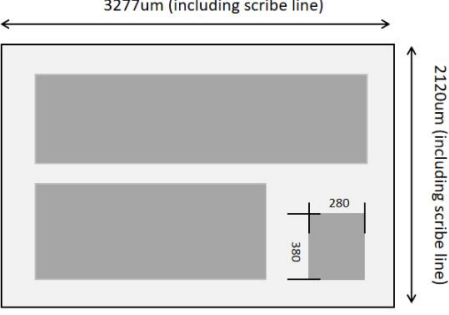


Wafer Specification

1. Order Information

Part No.	Description	Gross die / per 8" wafer
XG0066(XG3012)	40V(V_{DS}) / $\pm 20V(V_{GS})$/ 198A(I_D) N-Channel Enhancement Mode SGT MOSFET	4,148

2. Physical Characteristics

	Die Size: 3277µm × 2120µm (including scribe line)
	Gate: 280µm × 380µm
	For PDFN5X6 package Suggest Bonding wire: Gate: 0.203 mil Clip Source: 0.203 mil Clip

3. Mechanical Data

Nominal Back Metal Composition, Thickness	Ti-Ni-Ag (1kÅ°-2kÅ°-10kÅ°)
Nominal Front Metal Composition, Thickness	ALCu (5.5µm)
Wafer Diameter	200mm, with 010 notch
Wafer Thickness	125µm
Scribe Line Width	100µm

4. Key Electrical Characteristics of Die (at $T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	40	-	-	V	V _{GS} =0V, I _D =250μA
I _D (Device Ref)	Continuous Drain Current	-	-	198	A	T _J =25°C
R _{DS(on)} (FT)	Static Drain-to-Source On-Resistance	-	1.1	1.4	mΩ	V _{GS} =10V, I _D =15A
V _{GS(th)}	Gate Threshold Voltage	-	1.6	2	V	V _{DS} =V _{GS} , I _D =250μA
I _{DSS}	Drain-to-Source Leakage Current	-	-	1	μA	V _{DS} =40V, V _{GS} =0V
I _{GSS}	Gate-to-Source Leakage Current	-	-	±10 0	nA	V _{GS} =±20V, V _{DS} =0V
E _{AS}	Single Pulsed Avalanche Energy	-	-	450	mJ	L=0.5mH, V _{DD} =20V
R _g	Gate Poly Resistance	-	2	-	Ω	V _{DS} =0V, V _{GS} =0, f=1MHZ
C _{iss}	Input Capacitance	-	4400	-	pF	V _{DS} =20V, V _{GS} =0, f=1MHZ
C _{oss}	Output Capacitance	-	1400	-	pF	
C _{rss}	Reverse Transfer Capacitance	-	60	-	pF	
T _J , T _{STG}	Operating and Storage Temperature	-55°C to 175°C Max				